



**P-Channel Enhancement Mode Power MOSFET**

**Description**

The PE3117F uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It can be used in a wide variety of applications. It is ESD protected.

**General Features**

- $V_{DS} = -30V$ ,  $I_D = -9.5A$

$R_{DS(ON)} < 22m\Omega @ V_{GS}=-10V$

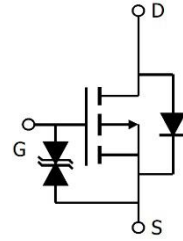
$R_{DS(ON)} < 32m\Omega @ V_{GS}=-4.5V$

ESD Rating:  $\geq 4000V$  HBM

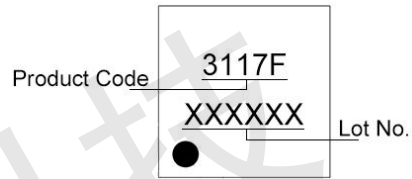
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

**Application**

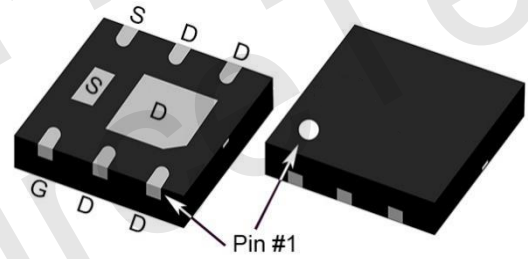
- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



UDFN2x2-6L

**Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-9.5	A
Drain Current-Continuous (TA=70°C )	$I_D$	-7	A
Pulsed Drain Current (Note 1)	$I_{DM}$	-38	A
Maximum Power Dissipation	$P_D$	2.8	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

**Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	45	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=-20V/+15V, V_{DS}=0V$	-	-	$\pm 10$	$\mu A$
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.9	-1.5	-2.1	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-4.5A$	-	17	22	m $\Omega$
		$V_{GS}=-4.5V, I_D=-4A$	-	23	32	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-10V, I_D=-4.1A$	-	20	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$C_{iss}$	$V_{DS}=-15V, V_{GS}=0V, F=10KHz$	-	235	-	pF
Output Capacitance	$C_{oss}$		-	180	-	pF
Reverse Transfer Capacitance (Note 4)	$C_{rss}$		-	25	-	pF
Gate Resistance	$R_g$		-	5	-	k $\Omega$
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=-15V, R_L=1\Omega, V_{GS}=-10V, R_G=3\Omega$	-	9	-	nS
Turn-on Rise Time	$t_r$		-	5	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	28	-	nS
Turn-Off Fall Time	$t_f$		-	13.8	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-15V, I_D=-4A, V_{GS}=-10V$	-	22	-	nC
Gate-Source Charge	$Q_{gs}$		-	3	-	nC
Gate-Drain Charge	$Q_{gd}$		-	7	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=-1A$	-	-	-1.2	V
Diode Forward Current (Note 2)	$I_S$		-	-	-5	A

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to product.



### Typical Electrical and Thermal Characteristics

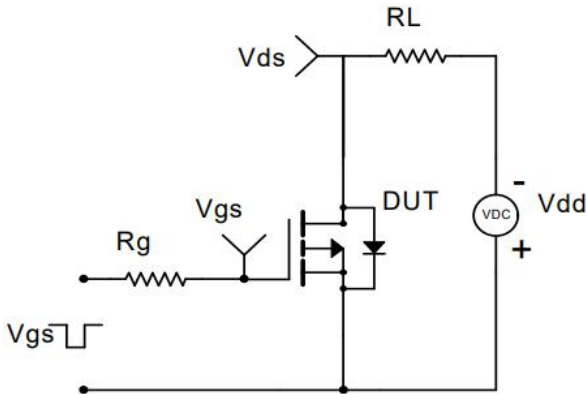


Figure 1 Switching Test Circuit

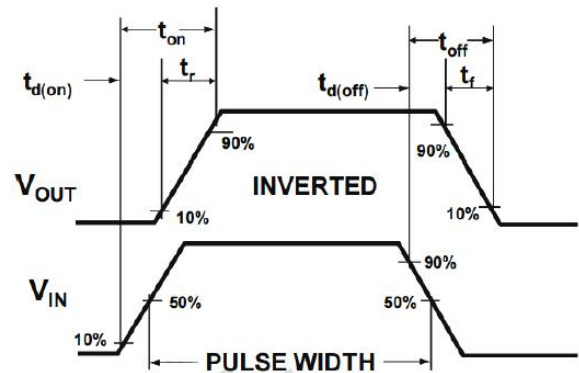


Figure 2 Switching Waveform

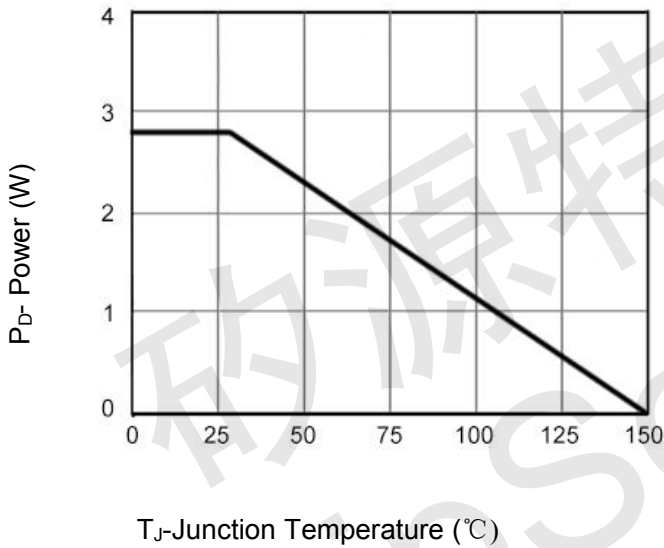


Figure 3 Power De-rating

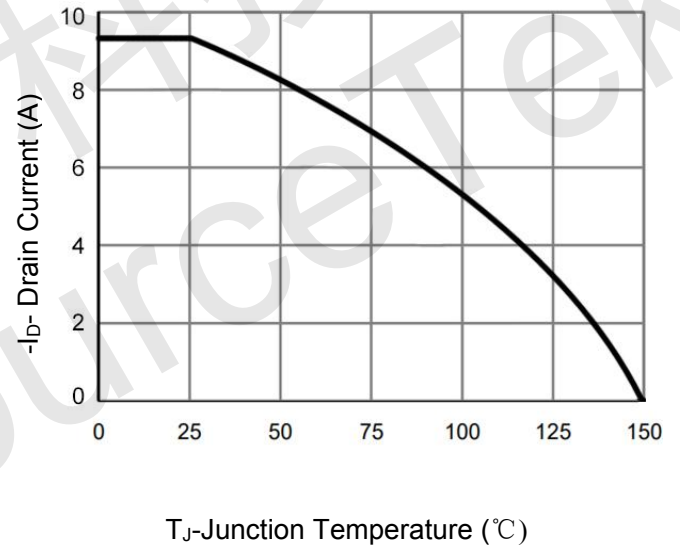


Figure 4 Drain Current

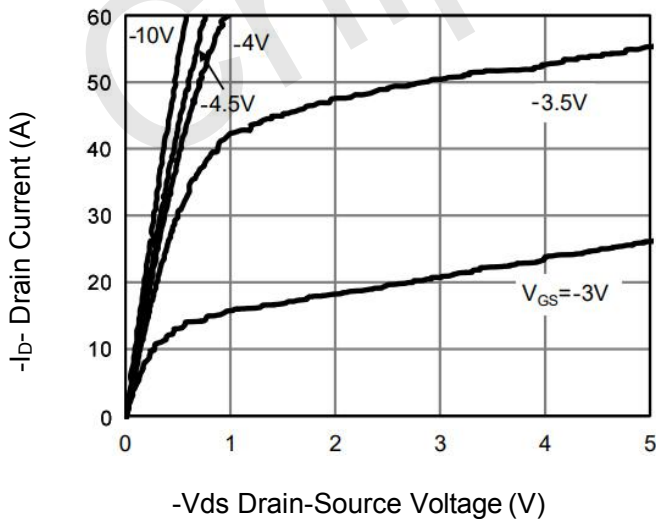


Figure 5 Output Characteristics

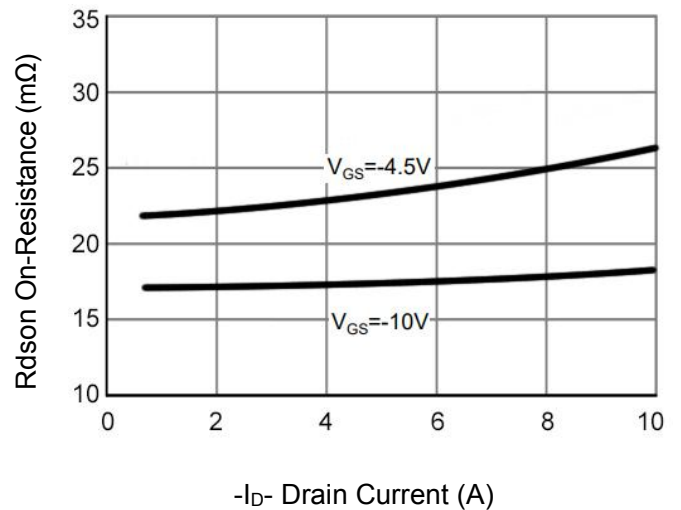
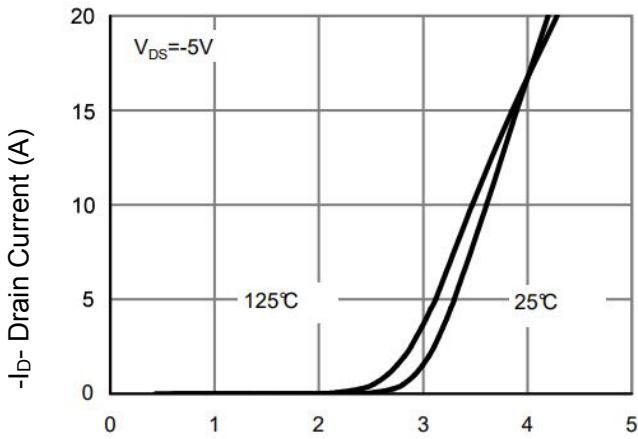
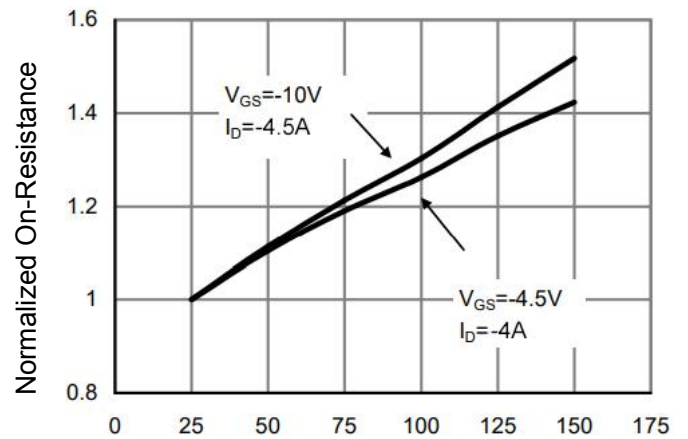


Figure 6 Rdson vs Drain Current



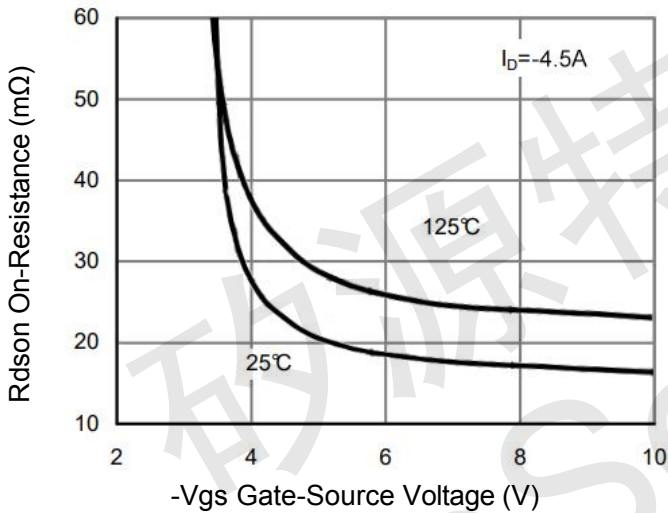
-Vgs Gate-Source Voltage (V)

Figure 7 Transfer Characteristics



TJ-Junction Temperature(°C)

Figure 8 Rdson vs Junction Temperature



-Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

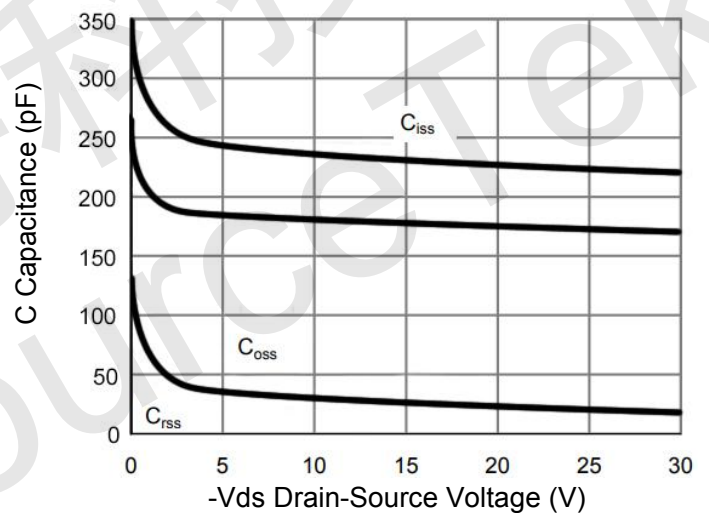


Figure 10 Capacitance vs Vds

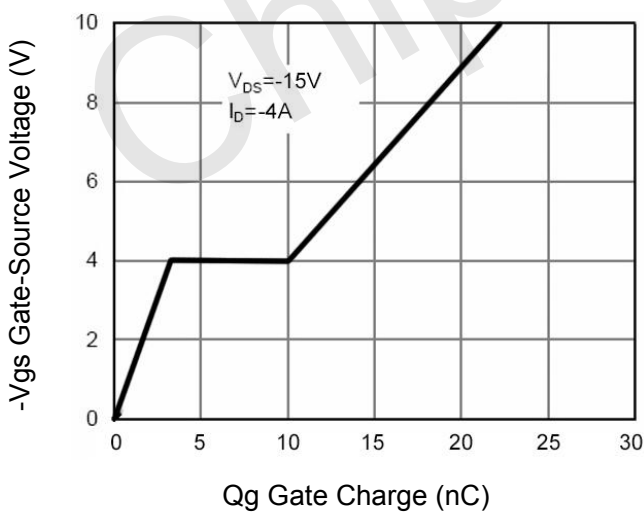


Figure 11 Gate Charge

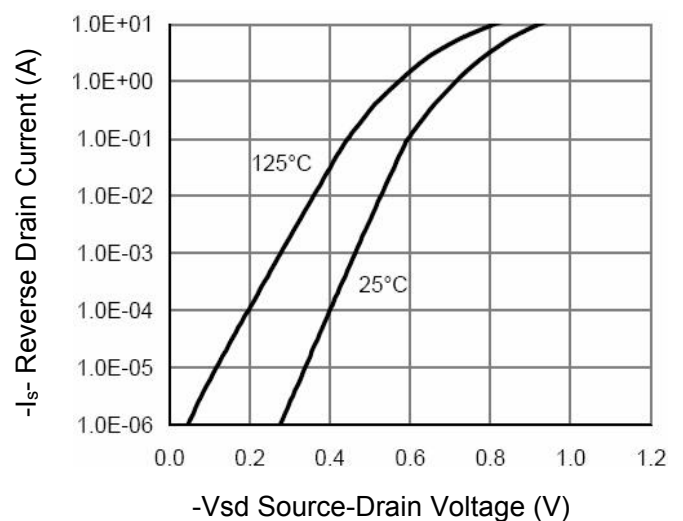


Figure 12 Source- Drain Diode Forward

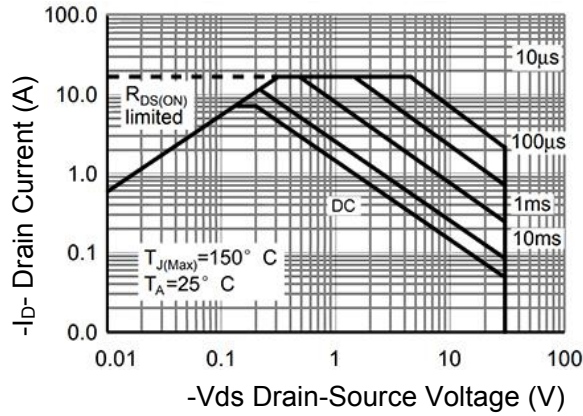


Figure 13 Safe Operation Area

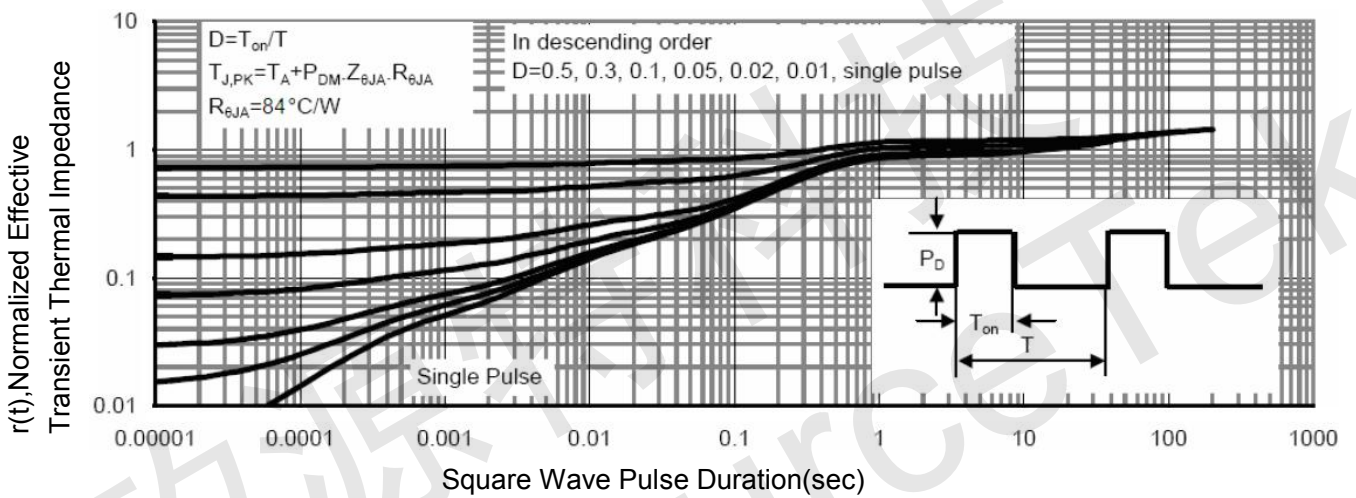


Figure 14 Normalized Maximum Transient Thermal Impedance



